

ABSTRACT

The film carrier tape for mounting electronic components according to the present invention comprises an insulating film and, on the surface thereof, an inner connection terminal, an outer connection terminal and a wiring for connecting these terminals and further comprises a solder resist layer covered in such a way that the connection terminals are exposed, and the tape secures electric connection of a connection terminal of an electronic component and the inner connection terminal by applying an ultrasonic wave on the inner connection terminal in mounting the electronic component,

wherein wiring positioned from a part where the inner connection terminal is electrically connected with the connection terminal of the electronic component to the edge of the solder resist layer and wiring in a 1000 μm length from the edge of the solder resist, which wiring is protected by the solder resist layer, are formed in an almost straight shape.

The film carrier tape for mounting electronic components having such a structure according to the present invention does not receive concentration of stress in application with an ultrasonic wave and thereby cracks or disconnection are hardly caused in the wiring pattern.